



# EMIF08-1005M16

## IPAD™

8 line low capacitance EMI filter and ESD protection in Micro QFN package

### Main product characteristics

Where EMI filtering in ESD sensitive equipment is required:

- LCD and CAMERA for Mobile phones
- Computers and printers
- Communication systems
- MCU Boards

### Description

The EMIF08-1005M16 is an 8 line highly integrated device designed to suppress EMI/RFI noise in all systems exposed to electromagnetic interference.

This filter includes an ESD protection circuitry, which prevents damage to the application when subjected to ESD surges up to 15 kV on the input or output pins.

### Benefits

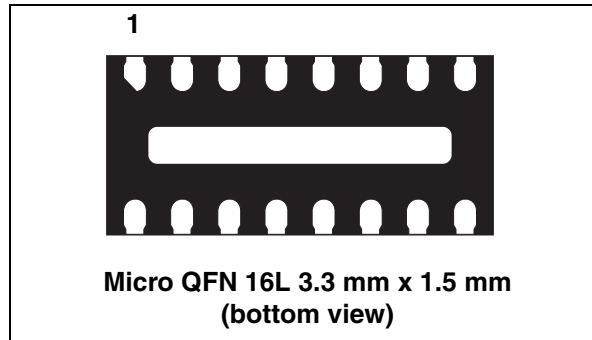
- EMI symmetrical (I/O) low-pass filter
- High efficiency in EMI filtering:
  - Greater than 34 dB attenuation at frequencies from 900 MHz to 1.8 GHz
- Cut-off frequency: 100 MHz
- Very low PCB space consuming: 3.3 mm x 1.5 mm
- Very thin package: 0.6 mm max.
- High efficiency in ESD suppression on inputs pins (IEC 61000-4-2 level 4).
- High reliability offered by monolithic integration
- High reduction of parasitic elements through integration
- Lead free package

### Complies with following standards:

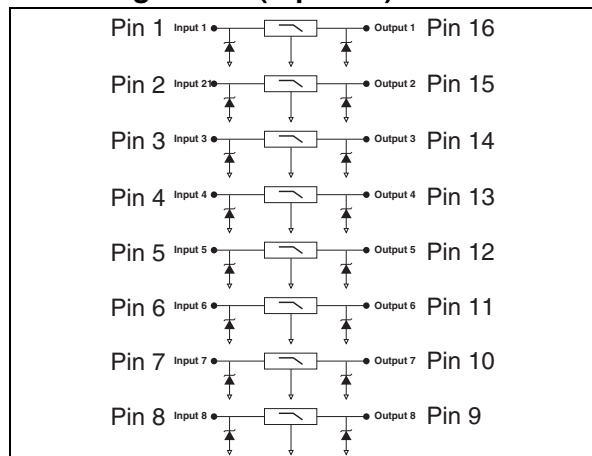
#### IEC 61000-4-2

level 4 input and output pins 15 kV (air discharge)  
8 kV (contact discharge)

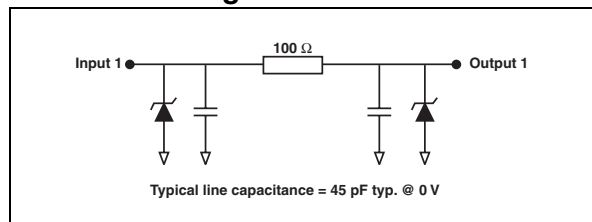
#### MIL STD 883E - Method 3015-6 Class 3 (all pins)



### Pin configuration (top view)



### Basic cell configuration



### Order code

| Part number    | Marking |
|----------------|---------|
| EMIF08-1005M16 | H8      |

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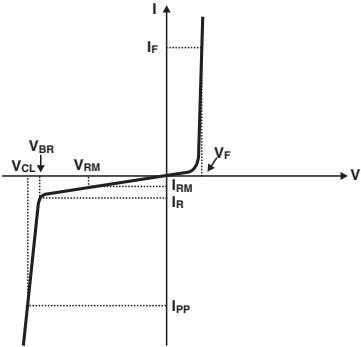
# 1 Characteristics

**Table 1. Absolute ratings (limiting values)**

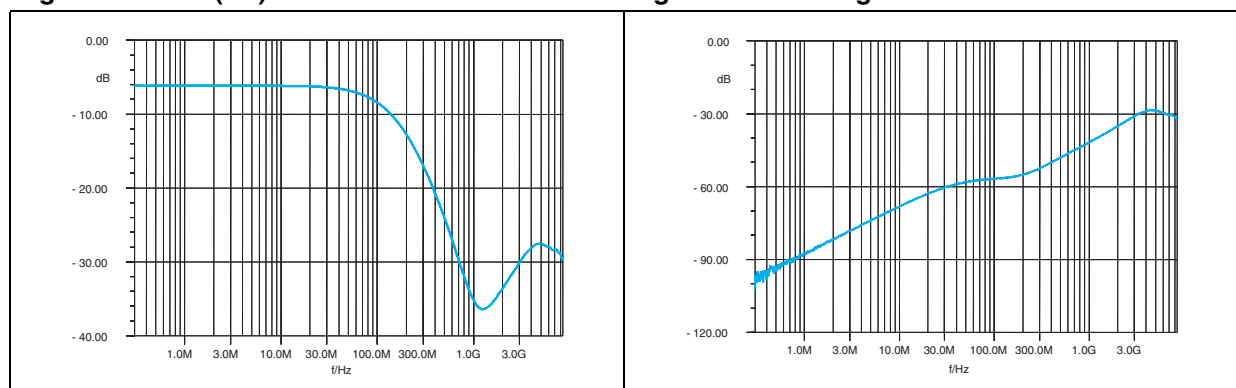
| Symbol    | Parameter   | Value         | Unit |
|-----------|---|---------------|------|
| $V_{PP}$  | ESD discharge IEC 61000-4-2 air discharge on input pins and output pins | 15            | kV   |
| $T_j$     | Maximum junction temperature  | 125           | °C   |
| $T_{Op}$  | Operating temperature range   | - 40 to + 85  | °C   |
| $T_{stg}$ | Storage temperature range   | - 55 to + 150 | °C   |

**Table 2. Electrical characteristics ( $T_{amb} = 25^\circ \text{C}$ )**

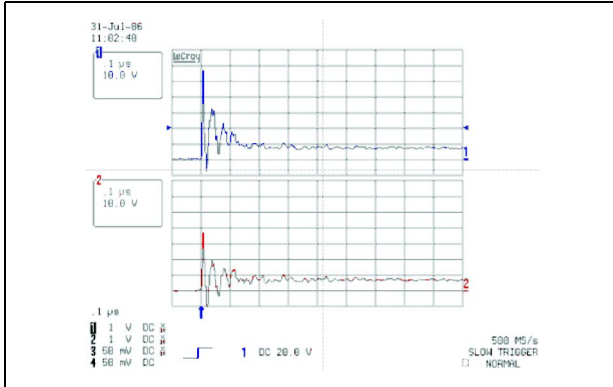
| Symbol     | Parameter                                |
|------------|--|
| $V_{BR}$   | Breakdown voltage                        |
| $I_{RM}$   | Leakage current @ $V_{RM}$               |
| $V_{RM}$   | Stand-off voltage                        |
| $V_{CL}$   | Clamping voltage                         |
| $R_d$      | Dynamic resistance                       |
| $I_{PP}$   | Peak pulse current                       |
| $R_{I/O}$  | Series resistance between Input & Output |
| $C_{line}$ | Input capacitance per line               |



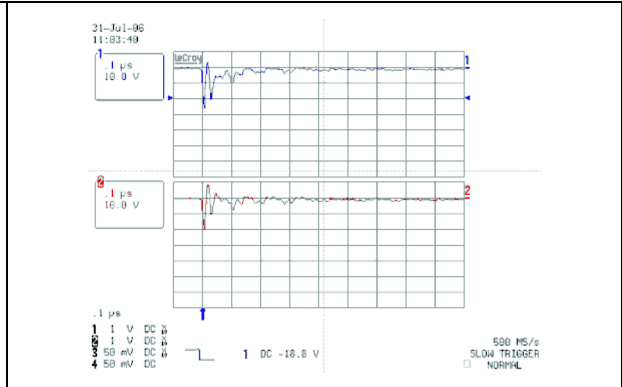
| Symbol     | Test conditions  | Min. | Typ. | Max. | Unit     |
|------------|--|------|------|------|----------|
| $V_{BR}$   | $I_R = 1 \text{ mA}$   | 6    | 8    | 10   | V        |
| $V_F$      | $I = 10 \text{ mA}$  | 0.5  | 1.0  | 1.5  | V        |
| $I_{RM}$   | $V_{RM} = 3 \text{ V per line}$  |      |      | 100  | nA       |
| $R_{I/O}$  | Tolerance $\pm 10\%$   | 90   | 100  | 110  | $\Omega$ |
| $C_{line}$ | $V_R = 0 \text{ V DC}$ , $V_{OSC} = 30 \text{ mV}$ , $F = 1 \text{ MHz}$ | 38   | 45   | 52   | pF       |

**Figure 1. S21(dB) attenuation measurement      Figure 2. Analog cross talk measurements**


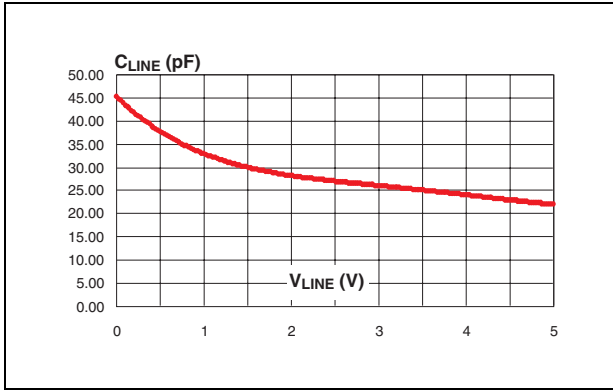
**Figure 3. ESD response to IEC 61000-4-2 (+15 kV air discharge) on one input ( $V_{in}$ ) and on one output ( $V_{out}$ )**



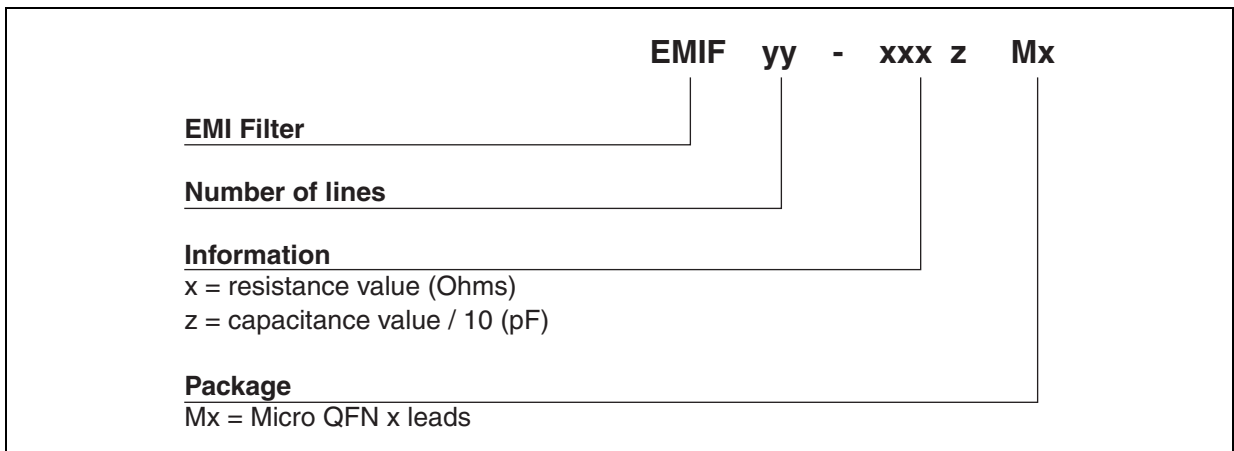
**Figure 4. ESD response to IEC 61000-4-2 (-15 kV air discharge) on one input ( $V_{in}$ ) and on one output ( $V_{out}$ )**



**Figure 5. Line capacitance versus reverse voltage applied (typical value)**



## 2 Ordering information scheme

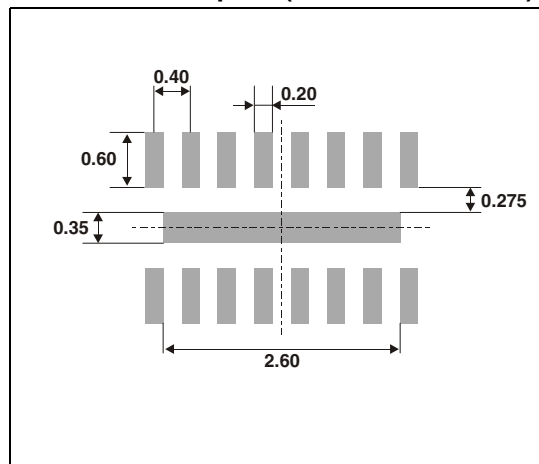


### 3 Package information

**Table 3. Micro QFN 3.3x1.5 16L dimensions**

| Ref. | Dimensions  |      |      |        |       |       |
|------|-------------|------|------|--------|-------|-------|
|      | Millimeters |      |      | Inches |       |       |
|      | Min.        | Typ. | Max. | Min.   | Typ.  | Max.  |
| A    | 0.50        | 0.55 | 0.60 | 0.020  | 0.022 | 0.024 |
| A1   | 0.00        | 0.02 | 0.05 | 0.000  | 0.001 | 0.002 |
| b    | 0.15        | 0.20 | 0.25 | 0.006  | 0.008 | 0.010 |
| D    | 3.20        | 3.30 | 3.40 | 0.126  | 0.130 | 0.134 |
| D2   | 2.45        | 2.60 | 2.70 | 0.096  | 0.102 | 0.106 |
| E    | 1.40        | 1.50 | 1.60 | 0.055  | 0.059 | 0.063 |
| E2   | 0.20        | 0.35 | 0.45 | 0.008  | 0.014 | 0.018 |
| e    |             | 0.40 |      |        | 0.016 |       |
| K    | 0.20        |      |      | 0.008  |       |       |
| L    | 0.20        | 0.30 | 0.40 | 0.008  | 0.012 | 0.016 |

**Figure 6. Micro QFN 3.3x1.5 16L footprint (dimensions in mm)**



**Figure 7. Marking**

Dot : Pin 1 Identification  
 X X= Marking  
 WW= DataCode (week)  
 Y=Data code(Year)  
 P= Assembly plant

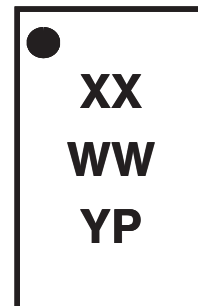
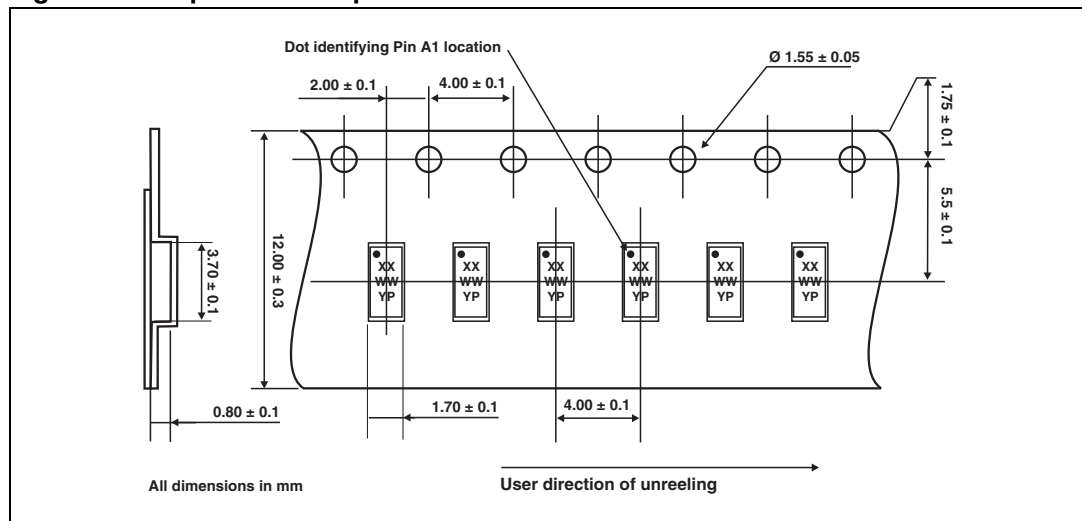


Figure 8. Tape and reel specification



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com).

## 4 Ordering information

| Part number    | Marking | Package   | Weight | Base qty | Delivery mode      |
|----------------|---------|-----------|--------|----------|--------------------|
| EMIF08-1005M16 | H8      | Micro QFN | 7.2 mg | 3000     | Tape and reel (7") |

## 5 Revision history

| Date        | Revision | Changes          |
|-------------|----------|------------------|
| 24-Oct-2006 | 1        | Initial release. |

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